

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yoshio Sakai	07/18/2017
RECEIVING PARTY DATA	
Name:	GOO CHEMICAL CO., LTD.
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City:	Uji-shi, Kyoto
State/Country:	Japan
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15568973
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ATTORNEY DOCKET NUMBER:	HOK-0649
NAME OF SUBMITTER:	LEE CHENG
SIGNATURE:	/Lee Cheng/
DATE SIGNED:	10/24/2017
Total Attachments: 1	
source=HOK-0649 Executed Assignment#page1.tif	

Docket No. _____

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

{Insert
ASSIGNEE's
Name(s)
Address(es)}

GOO CHEMICAL CO., LTD. of 58, Ijiri, Iseda-cho, Uji-shi,
Kyoto 611-0043, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE all of the right, title and interest to the invention entitled

{Title of
Invention}

LIQUID SOLDER RESIST COMPOSITION AND PRINTED WIRING BOARD
(filed as PCT International Application No. PCT/JP2016/004532)

{*If the assignment
is being filed
after the filing of the
application, this
section must be
completed}

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

*filed on _____, Serial No. _____

(Cheng Law Group, PLLC is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, division, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

{Signature(s)
of Assignor(s)}

Yoshio Sakai
(SIGNATURE)

Yoshio SAKAI
(TYPE NAME)

July 18, 2017
(DATE)